BST-505-0.3MM

ESFERAS PARA REBALLING 0.3mm 65.8g

0.2mm

0.25mm

0.3mm

0.35mm

0.4mm

0.45mm

0.5mm

0.55mm

0.6mm

0.65mm

Brand:	BST	Name:	solder ball
Ingredients:	alloy:Sn63/Pb37	Size:	16*35mm
Specifications:	0.2mm (55.4g/10bottle), 0.25mm (68.5G/10bottle), 0.3mm (65.8G/10bottle), 0.35mm (74G/10bottle), 0.4mm (86.3G/10bottle), 0.45mm (100.8 G/10bottle), 0.5mm (119.7G/bottle10), 0.55mm (142.7G/10bottle), 0.6mm (167.7G/10bottle)		
Quantity:	25,000 / bottle		
Features:	Tin ball is mainly connected to semiconductor wafers and circuit		
	boards and PCB boards, and small ball type tin electronic parts that transmit electronic signals.		

A bottle of 25,000

BST-505

High: **35mm**

Width: **16mm**


BEST
倍思特
MADE IN CHINA